



SOT1746-2

plastic, heatsink small outline package; 32 terminals; 0.65 mm pitch; 11 mm x 7.5 mm x 2.3 mm body

15 January 2021

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP32
Package type industry code	HSOP32
Package style descriptive code	HSOP (heatsink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-01-2021
Manufacturer package code	98ASA00368D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.9	11	11.1	mm
package width	7.4	7.5	7.6	mm
seated height	2.22	2.3	2.45	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	32	-	



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2 Package outline

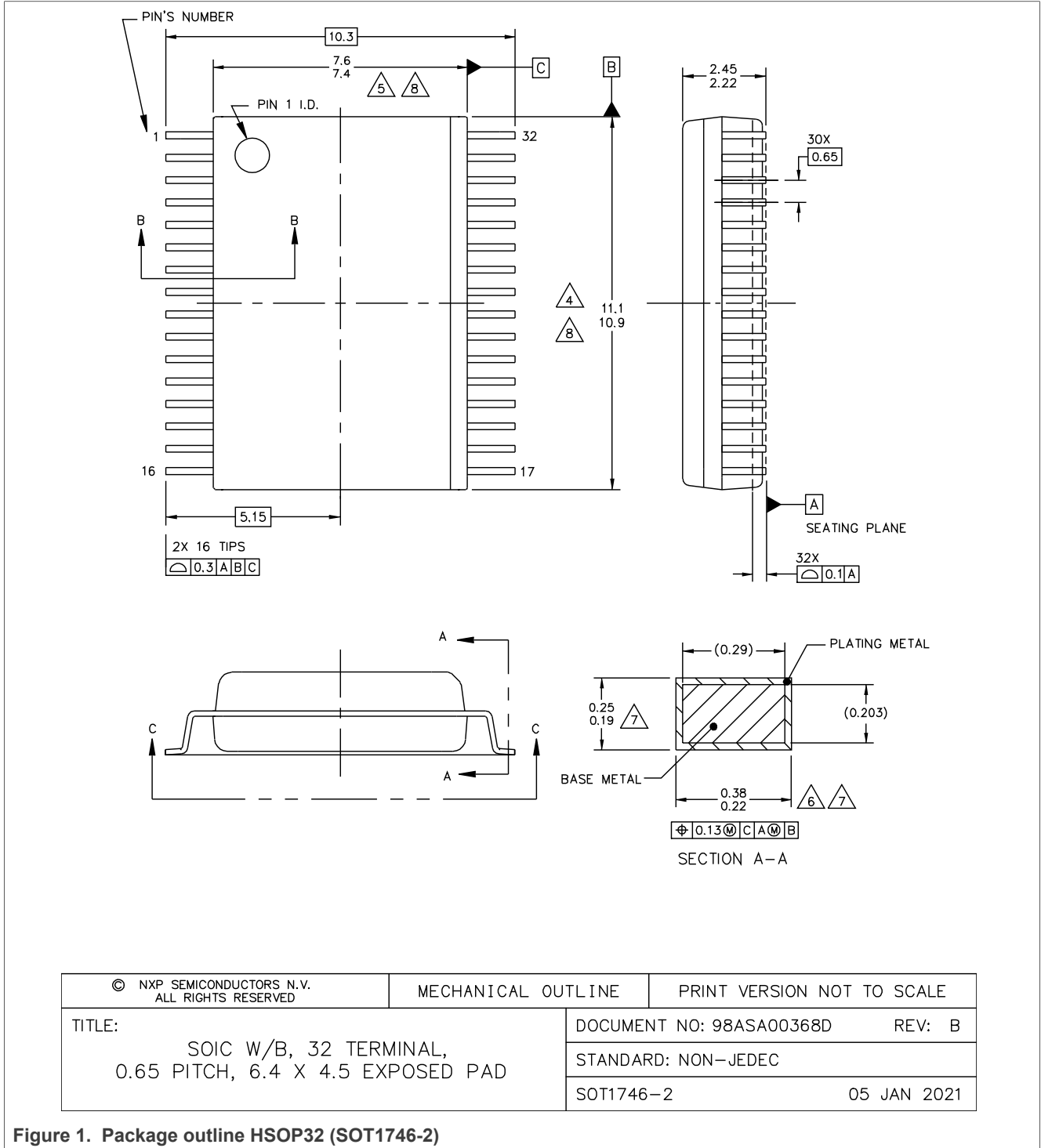


Figure 1. Package outline HSOP32 (SOT1746-2)

plastic, heatsink small outline package; 32 terminals; 0.65 mm pitch; 11 mm x 7.5 mm x 2.3 mm body

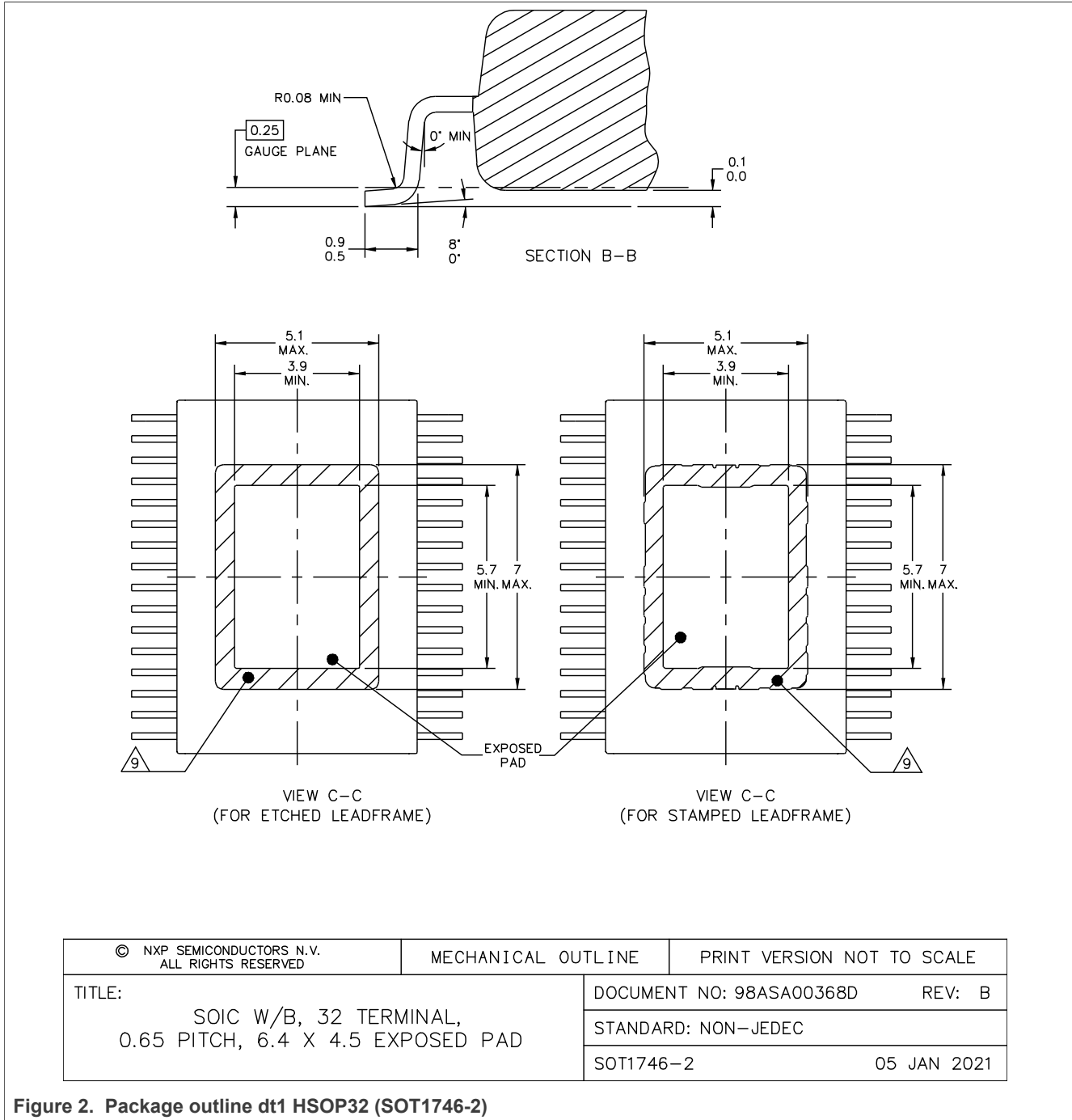


Figure 2. Package outline dt1 HSOP32 (SOT1746-2)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS B AND C TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
5. THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.4 mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT LESS THAN 0.07 mm.
7. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.3 mm FROM THE LEAD TIP.
8. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. THIS DIMENSION IS DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTER-LEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
9. HATCHED AREA TO BE KEEP-OUT ZONE FOR PCB ROUTING.

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TITLE: SOIC W/B, 32 TERMINAL, 0.65 PITCH, 6.4 X 4.5 EXPOSED PAD		DOCUMENT NO: 98ASA00368D	REV: B
		STANDARD: NON-JEDEC	
		SOT1746-2	05 JAN 2021

Figure 3. Package outline note HSOP32 (SOT1746-2)

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3 Legal information

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